

2007 — HIROSE Akio

Scientific Papers/Commentary Articles

1. H. Tatsumi, Y. Akada, T. Yamaguchi and A. Hirose, Sintering Mechanism of Composite Ag Nanoparticles and its Application to Bonding Process -Effects of Ag₂CO₃ Contents on Bondability to Cu-, *Advanced Materials Research*, 26-28, pp.499-502, 2007
2. T. Sano, K. Takahashi, A. Hirose, O. Sakata, M. Okoshi, N. Inoue, and K. F. Kobayashi, Femtosecond Laser Synthesis of Polymorphic Diamond from Highly Oriented Pyrolytic Graphite, *Mater. Sci. Forum*, 561-565, 2349-2352, 2007
3. M. Tsujino, T. Sano, N. Ozaki, O. Sakata, M. Okoshi, N. Inoue, R. Kodama, and A. Hirose, Femtosecond Laser Synthesis of High-Pressure Phases of Si, *Advanced Materials Research*, 26-28, 1291-1294, 2007
4. Akio Hirose, Hiroki Imaeda, Miki Kondo and Kojiro F. Kobayashi, Influence of Alloying Elements on Interfacial Reaction and Strength of Aluminum/Steel Dissimilar Joints for Light Weight Car Body, *Materials Science Forum*, 539-543, 3888-3893, 2007
5. Tomokazu Sano, Kengo Takahashi, Akio Hirose and Kojiro F. Kobayashi, Femtosecond Laser Ablation of Zr₅₅Al₁₀Ni₅Cu₃₀ Bulk Metallic Glass, *Materials Science Forum*, 539-543, 1951-1954, 2007

International Conference Proceedings

1. Yusuke Akada, Hiroaki Tatsumi, Takuto Yamaguchi, Akio Hirose, Toshiaki Morita, and Eiichi Ide, Investigation of Bonding Mechanism of Ag Nanoparticles to Bulk Metals, *Proceedings of SPT'07*, in press, 2007
2. Hidetaka Umeshita, Hiroki Imaeda, Akio Hirose, and Kojiro F. Kobayashi, Effects of alloying elements on interfacial properties of dissimilar joint of aluminum alloy and steels, *Proceedings of SPT'07*, in press, 2007
3. Masashi Tsujino, Tomokazu Sano, Norimasa Ozaki, Osami Sakata, Masayuki Okoshi, Narumi Inoue, Ryouyusuke Kodama, and Akio Hirose, Synthesis of High-Pressure Phases of Silicon Using Femtosecond Laser Driven Shock Wave, *Proceedings of SPT'07*, in press, 2007

Awards

1. A. Hirose, E. Ede, S. Angata, S. Kobayashi and K. F. Kobayashi, Outstanding Technical Paper Award of International Conference on Electronics Packaging 2006, 2007/4/18